

ABSTRACT

5 A method for singulating a substrate containing
semiconductor components is performed using a nest for
holding the substrate, a prestage alignment base for aligning
the substrate during a prestage alignment step, and a vacuum
cutting base for holding the nest and the substrate during a
cutting step. The prestage alignment base includes locator
10 pins configured to engage locator openings on the substrate
to align the substrate on the nest. As the cutting base does
not include the locator pins, the cutting step can be
performed without saw scrap collecting on the locator pins.
A system for performing the method includes the nest and the
15 prestage alignment base having the locator pins configured to
engage the locator openings on the substrate. The system
also includes the sawing base which includes pedestals with
vacuum conduits for holding the substrate stationary on the
nest for sawing. The system also includes the saws, and a
20 vacuum source in flow communication with the vacuum conduit
and pedestals on the sawing base.